

a copper conductor within the trench or hole and on the first diffusion barrier,
with the second diffusion barrier having lesser wettability with copper than
the [zinc oxide material] first diffusion barrier.

32 (Amended)

An integrated-circuit assembly comprising:

an insulative layer having opposing first and second major surface, with the first major surface having a trench or hole, the trench or hole having an edge;
a first diffusion barrier having an in-portion lining the trench or hole and having an out-portion outside the trench or hole and on the first major surface, with the out-portion having an edge adjacent the edge of the trench or hole, the first diffusion barrier consisting essentially of tungsten, titanium-tungsten, or titanium nitride;
a second diffusion barrier on the out-portion of the first diffusion barrier [insulative layer] and having an edge substantially flush with a least a portion of the edge of the [trench or hole] first diffusion barrier;
a copper conductor within the trench or hole and on the first diffusion barrier, with the second diffusion barrier having lesser wettability with copper than the [zinc oxide material] first diffusion barrier.

REMARKS

Claims 38-76 are pending in the application. Of these, claims 38-45 stand allowed, claims 60, 61, 74, and 75 stand allowable if rewritten in appropriate independent form, claims 46-55 stand rejected under 35 USC §112, and claims 56-59 and 62-73 and 76 stand rejected under 35 USC §102.

Information Disclosure Statements

Applicant respectfully requests that initialed copies of the 1449 Forms submitted with the Information Disclosure Statements filed on **March 26, 2001** and **May 16, 2001**, acknowledging consideration of the identified references, be returned with the next official communication.